

## Build Up HDI (Standard)

HDI04\_1+2+1\_0,80\_35\_engl

**4 - Layers**

Core: 0,61 mm Cu 35/35 µm



**WE-Article No.:**  

1 + 2 + 1

**Customer:**  

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[µm]	[µm]	
	TOP/VS			Foil	12 µm	1)	12	
						1 x 1080	60	
	2				35 µm		33	
				0,610 mm			610	
	3				35 µm		33	
						1 x 1080	60	
	BOT/RS			Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

**total material thickness: 820**

Note: Lamination thickness for Prepregs depending on layout characteristics.

<b>final lamination thickness:</b>	<b>0,80</b>	+/-	0,08	mm		Date:	Engineer:
thickness with electro plated Cu:	0,89	+/-	0,11	mm			
total thickness with soldermask	0,95	+/-	0,13	mm			
customer requirement		+/-		mm	point:		
prepared: on		checked: on		approved: on		revision	
04.01.2006	S. Keller	04.05.2006	M.Kress	04.01.2006	R. Schönholz	00	page: 4+